

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK,UL94V-0.
- 1.2 CONTACT: PHOSPHOR BRONZE,GOLD (SEE P/N) PLATED IN CONTACT AREA, 80u" MIN MATTE TIN PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS,80u" MIN. MATTE TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING:1.5A;
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC/MINUTE.
- 2.3 CONTACT RESISTANCE: 50mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE:-40°C TO +105°C.

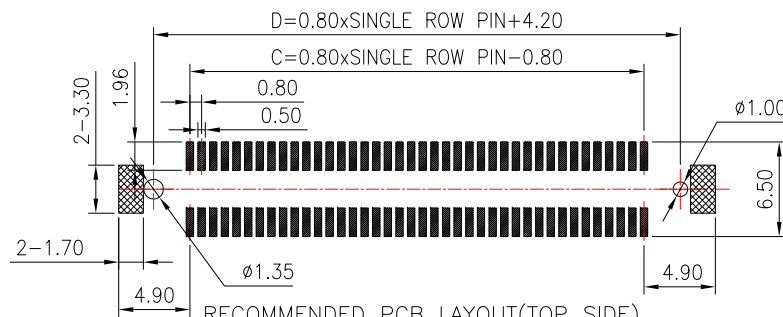
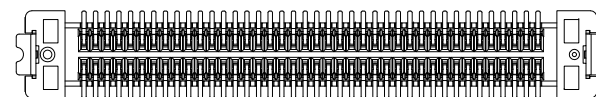
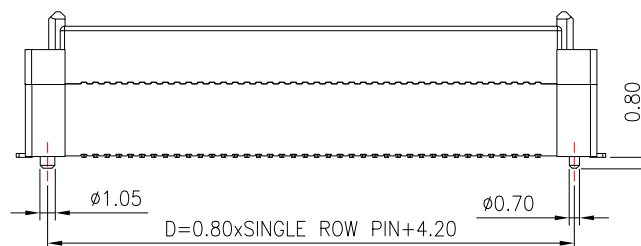
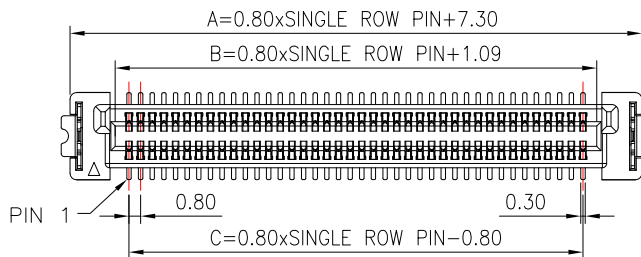
3.ORDER INFORMATION:

66C2-F XXX XX XXX R 01

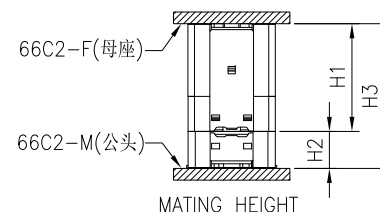
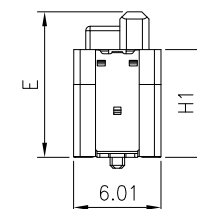
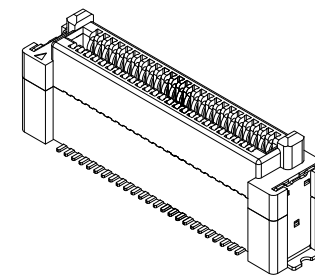
Pin数码	端子电镀:	塑胶高度:	包装方式:
SEE TABLE	S0=Gold Flash/Tin(半金锡)	050=5.0mm("E")	R=TAPE REEL
	S1=1u" Gold/Tin	060=6.0mm("E")	
	S2=3u" Gold/Tin	100=10.0mm("E")	
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

TABLE1:

No. OF PIN	A	B	C	D
010:2x5PIN	11.30	5.09	3.20	8.20
020:2x10PIN	15.30	9.09	7.20	12.20
030:2x15PIN	19.30	13.09	11.20	16.20
040:2x20PIN	23.30	17.09	15.20	20.20
050:2x25PIN	27.30	21.09	19.20	24.20
060:2x30PIN	31.30	25.09	23.20	28.20
080:2x40PIN	39.30	33.09	31.20	36.20
100:2x50PIN	47.30	41.09	39.20	44.20
140:2x70PIN	63.30	57.09	55.20	60.20



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05



MATING HEIGHT

MATING HEIGHT	E	H1	H2	H3
5.00mm	5.00	2.45	2.55	5.00
10.00mm			7.55	10.00
15.00mm			12.55	15.00
6.00mm	6.00	3.45	2.55	6.00
11.00mm			7.55	11.00
16.00mm			12.55	16.00
10.00mm	10.00	7.45	2.55	10.00
15.00mm			7.55	15.00
20.00mm			12.55	20.00

OPERATION		DRAW	WLY	2019.08.30
X.X	±0.40	DESIGN	Jensen	2019.08.30
X.XX	±0.25	CHECK	Jack	2019.08.30
X.XXX	±0.15	APPROVE	Andy	2019.08.30
Angle	±3°			
DIM.	TOL	UNIT	mm	SCALE 1:1

SOLEPIN 东莞市硕品电子有限公司
Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	SIZE	A4	PART NO.	66C2-FXXXXXXXR01
AO		NEW			SHEET	1/1	TITLE:	BTB PITCH 0.8mm 母座直立式SMT TYPE
					PROJ.		DRAW NO.	SP-095

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK,UL94V-0.
- 1.2 CONTACT: BRASS,GOLD 1u" MIN PLATED IN CONTACT AERA, GOLD 1u" MIN PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS,80u" MIN. MATTE TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

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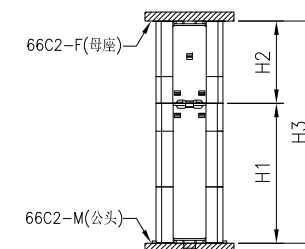
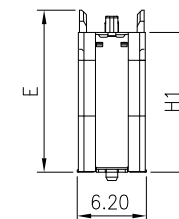
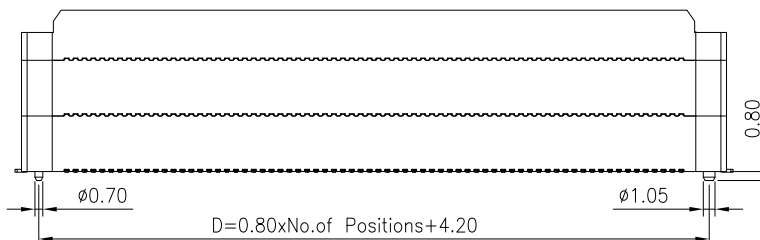
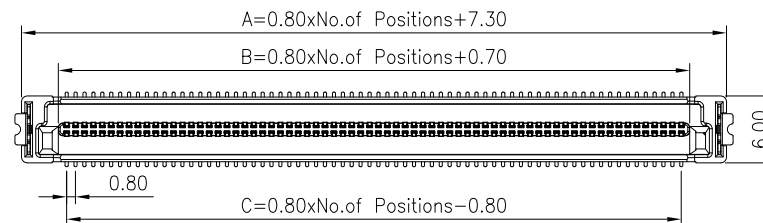
3. ORDER INFORMATION:

66C2-M XXX XX XXX R 01

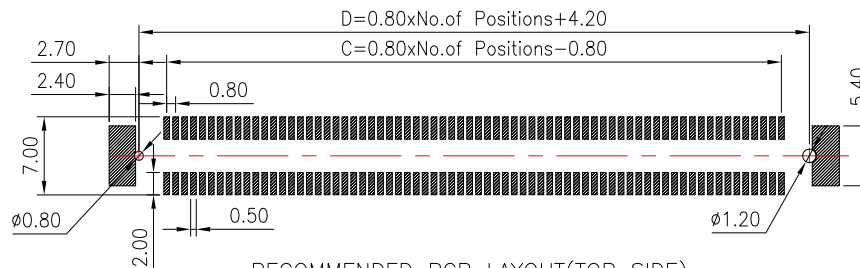
Pin数码	端子电镀:	塑胶高度:	包装方式:
SEE TABLE	S0=Gold Flash/Tin	045=4.50mm("E")	R=TAPE REEL
	S1=1u" Gold/Tin	095=9.50mm("E")	
	S2=3u" Gold/Tin	145=14.50mm("E")	
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

TABLE1:

No. OF PIN	A	B	C	D
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050:2x25PIN	27.30	20.70	19.20	24.20
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080:2x40PIN	39.30	32.70	31.20	36.20
100:2x50PIN	47.30	40.70	39.20	44.20
140:2x70PIN	63.30	56.70	55.20	60.20



MATING HEIGHT



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF $\pm$ 0.05

MATING HEIGHT	E	H1	H2	H3
5.00mm	4.55	2.55	2.45	5.00
6.00mm			3.45	6.00
10.00mm			7.45	10.00
10.00mm	9.55	7.55	2.45	10.00
11.00mm			3.45	11.00
15.00mm			7.45	15.00
15.00mm	14.55	12.55	2.45	15.00
16.00mm			3.45	16.00
20.00mm			7.45	20.00

					OPERATION		DRAW		WLY		2021.03.21		SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD			
					X.X	±0.40	DESIGN		Jensen		2021.03.21					
					X.XX	±0.25	CHECK		Jack		2021.03.21					
					X.XXX	±0.15	APPROVE		Andy		2021.03.21					
A0		NEW	_____	_____	Angle	±3°	APPROVE		Andy		2021.03.21		SHEET	1/1	TITLE:	0.8mm BTB 公头直立式SMT TYPE
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM.	TOL	UNIT		mm	SCALE	1:1	PROJ.		DRAW NO.	SP-265	